

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended) A multilayer ceramic electronic part having

an external electrode(s) formed from a thermosetting conductive paste which is then cured, said thermosetting conductive paste comprising conductive particles having a high melting point of 400°C or more, metal powder having a melting point of 300°C or less and a thermosetting resin(s), and wherein the metal powder having a melting point of 300 °C or less is present in an amount by weight based on the total weight of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less, of from 5% to 17.6% and

an internal electrode(s) comprising Ni.

**2. (original)** The multilayer ceramic electronic part according to claim 1, wherein the total content of said conductive particles having a high melting point and said metal powder having a melting point of 300 °C or less in said thermosetting conductive paste is in the range of 70 to 95% by weight relative to the total weight of said conductive particles having a high melting point, said metal powder having a melting point of 300 °C or less, and said resin(s).

**3. (Canceled)**

**4. (Currently amended)** A multilayer ceramic electronic part obtained according to a method comprising the steps of:

(1) providing a thermosetting conductive paste comprising conductive particles having a high melting point of 400°C or more, metal powder having a melting point of 300 °C or less and a thermosetting resin(s), and a ceramic composite body, having an internal electrode(s) comprising Ni, which composite body is to be provided with an external electrode(s);

(2) printing or applying said thermosetting conductive

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paste on or to a surface(s) where an internal electrode(s) of said ceramic composite body is led out; and

(3) maintaining said ceramic composite body obtained in the step (2) at a temperature of 80 °C to 400 °C for a period of one to sixty minutes so as to cure said thermosetting conductive paste and form the external electrode(s); and wherein the metal powder having a melting point of 300°C or less is present in an amount by weight based on the total weight of said conductive particles having a high melting point and said metal powder having a melting point of 300°C or less, of from 5% to 17.6%.

**5. (Currently amended)** The multilayer ceramic electronic part according to claim 4, wherein said conductive particle in said external electrode(s) makes a diffused junction with ~~a metal~~ the Ni of said internal electrode(s) of said multilayer ceramic composite body.

**6. (Previously presented)** The multilayer ceramic electronic part according to claim 4, wherein said multilayer ceramic electronic part is selected from the group consisting of a capacitor, a capacitor array, a thermistor, a varistor, an LC composite part,

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a CR composite part, an LR composite part, and an LCR composite part.

**7. (Canceled)**